

Features :

- Isolated mounting base 2500V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

Typical Applications

- Various rectifiers
- DC supply for PWM inverter

V _{RSM}	V _{RPM}	Type & Outline
900V	800V	MDx260-08
1100V	1000V	MDx260-10
1300V	1200V	MDx260-12
1500V	1400V	MDx260-14
1700V	1600V	MDx260-16
1900V	1800V	MDx260-18

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _J (°C)	VALUE			UNIT
				Min	Type	Max	
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side cooled, T _C =100°C	150			260	A
I _{F(RMS)}	RMS forward current		150			408	A
I _{RPM}	Repetitive peak current	at V _{RPM}	150			20	mA
I _{FSM}	Surge forward current	10ms half sine wave	150			9.5	KA
I ² t	I ² T for fusing coordination	V _R =0.6V _{RPM}				451	A ² s*10 ³
V _{FO}	Threshold voltage		150			0.72	V
r _F	Forward slop resistance					0.40	mΩ
V _{FM}	Peak forward voltage	I _{FM} =800A	25			1.45	V
R _{th(j-c)}	Thermal resistance Junction to case	At 180° sine Single side cooled per chip				0.120	°C /W
R _{th(c-h)}	Thermal resistance case to heatsink	At 180° sine Single side cooled per chip				0.04	°C /W
V _{iso}	Isolation voltage	50Hz, R.M.S, t=1min, I _{iso} :1mA(max)		2500			V
F _m	Terminal connection torque(M8)				12.0		N·m
	Mounting torque(M6)				6.0		N·m
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight				600		g
Outline	M03Y						

Peak forward Voltage Vs. Peak forward Current

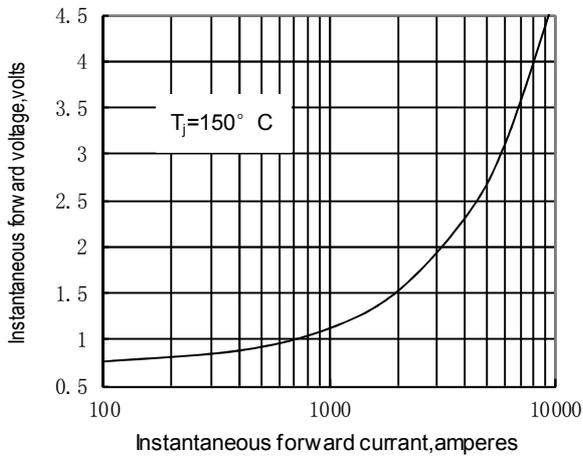


Fig.1

Max. junction To case Thermal Impedance Vs. Time

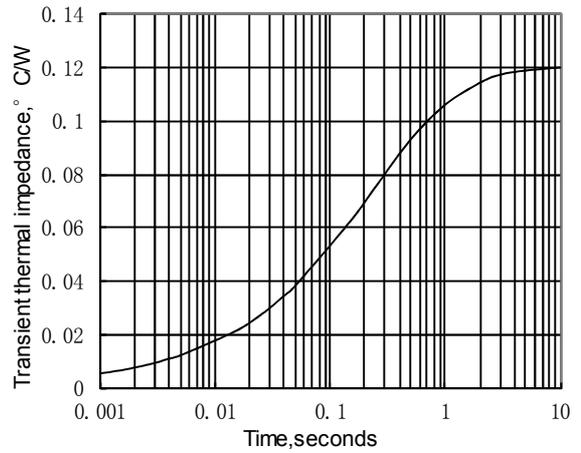


Fig.2

Max. Power Dissipation Vs. Mean forward Current

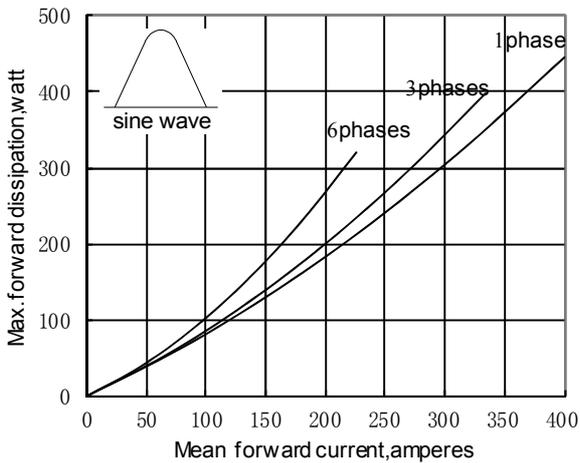


Fig.3

Max. case Temperature Vs. Mean forward Current

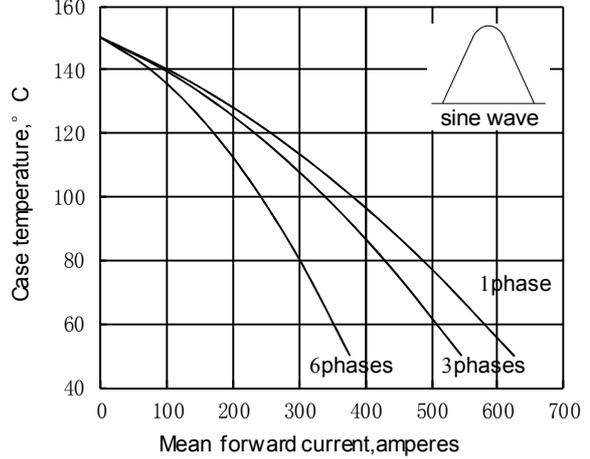


Fig.4

Max. Power Dissipation Vs. Mean forward Current

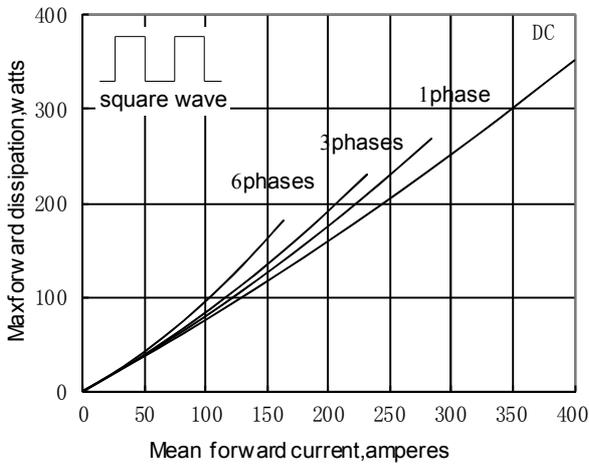


Fig.5

Max. case Temperature Vs. Mean forward Current

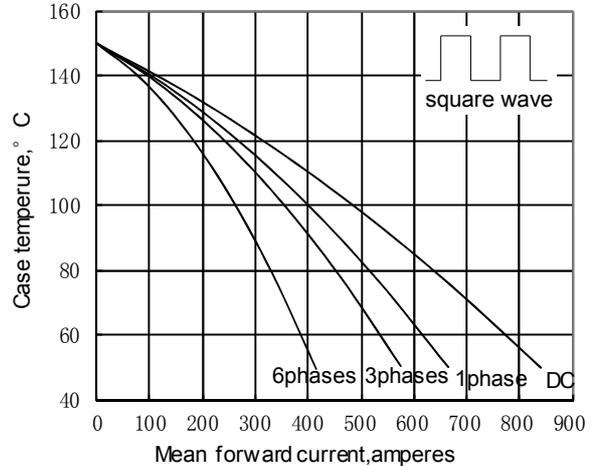


Fig.6

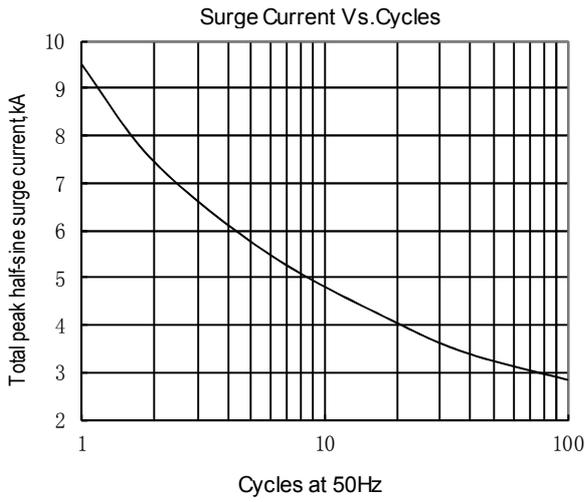


Fig.7

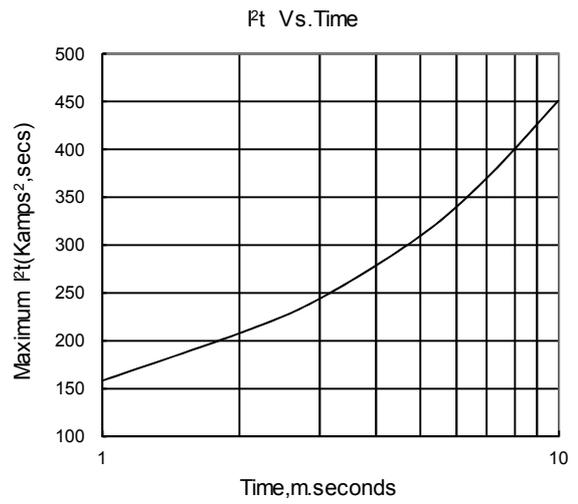
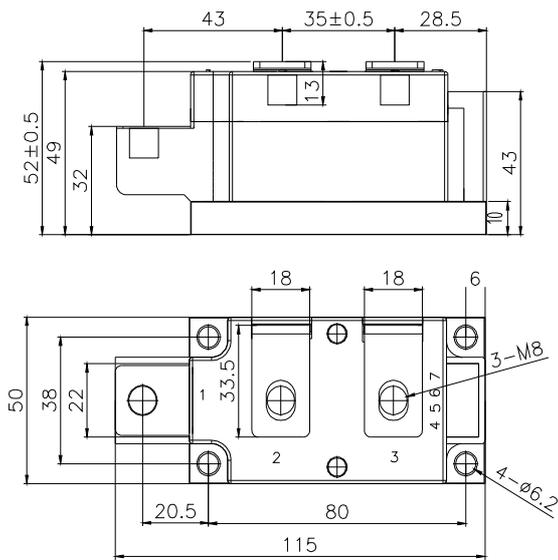


Fig.8

Outline:



M03Y

